

**Amendments to the Claims:**

Please cancel claims 7-15 and amend claims 1, 2 and 6, as follows. The following listing of claims will replace all prior versions, and listings, of claims in the application.

**Listing of Claims:**

Claim 1 (Currently Amended). A holding and conveyance jig for detachably holding and conveying a printed circuit board on which electronic components are mounted ~~or a conductive material laminated plate for manufacturing said printed circuit board,~~  
5 said jig comprising:

a plate which has a weak-adherence adhesive pattern on a surface of the plate; wherein:

said printed circuit board has a conductive portion and a non-conductive portion on a surface of the printed circuit board,  
10 and said printed circuit board ~~or said conductive material laminated plate~~ is placed and held on the surface of said plate, and

said weak-adherence adhesive pattern is formed at a position corresponding to said non-conductive portion.

Claim 2 (Currently Amended). A holding and conveyance jig for detachably holding and conveying a printed circuit board on

which electronic components are mounted ~~or a conductive material~~  
~~laminated plate for manufacturing said printed circuit board,~~

5 said jig comprising:

a plate which has a weak-adherence adhesive layer on a  
surface of the plate; wherein:

said printed circuit board has a conductive portion and a  
non-conductive portion on a surface of the printed circuit board,  
10 and said printed circuit board ~~or said conductive material~~  
~~laminated plate~~ is placed and held on the surface of said plate,  
and

a weak-adherence adhesive pattern subjected to surface  
roughening is formed on a surface of said weak-adherence adhesive  
15 layer at a position corresponding to said conductive portion.

Claim 3 (Previously Presented). The holding and conveyance  
jig according to claim 1, wherein said weak-adherence adhesive  
pattern has a plurality of thickness regions differing in  
thickness from the surface of said plate.

Claim 4 (Previously Presented). The holding and conveyance  
jig according to claim 1, wherein said weak-adherence adhesive  
pattern has a plurality of adhesive strength regions differing in  
adhesive strength.

Claim 5 (Previously Presented). The holding and conveyance jig according to claim 2, wherein a non-adhesive pattern is formed at a position corresponding to said conductive portion on the surface of said weak-adherence adhesive layer.

Claim 6 (Currently Amended). A method of conveying a printed circuit board ~~on which~~ comprising the steps of:

providing on said printed circuit board electronic components which are mounted thereon, said printed circuit board  
5 having on a surface thereof and which has a conductive portion and a non-conductive portion ~~on a surface of the printed circuit board, and~~

conveying said printed circuit board while detachably holding said printed circuit board on a surface of a holding and  
10 conveyance jig in which a weak-adherence adhesive pattern is provided on ~~[[a]]~~ the surface of the jig, ~~the method comprising the step of:~~

~~— holding said printed circuit board on the surface of said holding and conveyance jig in a manner such that said~~  
15 non-conductive portion is placed by being restricted to a surface of said weak-adherence adhesive pattern.

Claims 7-15 (Cancelled).

Claim 16 (Previously Presented). The holding and conveyance  
jig according to claim 2, wherein said weak-adherence adhesive  
5 pattern has a plurality of thickness regions differing in  
thickness from the surface of said plate.

Claim 17 (Previously Presented). The holding and conveyance  
jig according to claim 2, wherein said weak-adherence adhesive  
pattern has a plurality of adhesive strength regions differing in  
adhesive strength.

Claim 18 (Previously Presented). The holding and conveyance  
jig according to claim 3, wherein said weak-adherence adhesive  
pattern has a plurality of adhesive strength regions differing in  
adhesive strength.

Claim 19 (Previously Presented). The holding and conveyance  
jig according to claim 16, wherein said weak-adherence adhesive  
pattern has a plurality of adhesive strength regions differing in  
adhesive strength.